ABSTRACT

INTEGRATED CIRCUIT PACKAGE IN PACKAGE SYSTEM WITH ADHESIVELESS PACKAGE ATTACH

An integrated circuit package in package system includes a package in package lead with a package in package lead surface substantially planar, attaching a first integrated circuit package having a first encapsulant surface substantially coplanar with the package in package lead surface, attaching a second integrated circuit near the first integrated circuit package, and forming a package in package encapsulant over the first integrated circuit package and the second integrated circuit. (Fig. 1)